

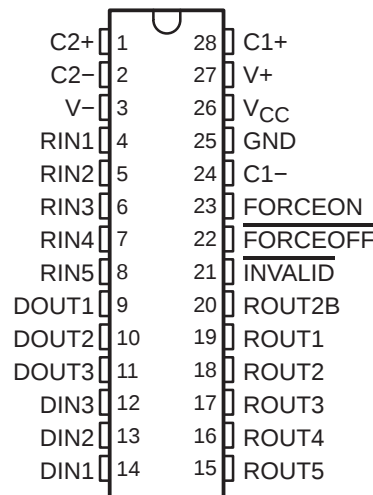
MAX3243

3-V TO 5.5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER WITH ± 15 -kV ESD (HBM) PROTECTION

SLLS350L – APRIL 1999 – REVISED MARCH 2004

- Single-Chip and Single-Supply Interface for IBM™ PC/AT™ Serial Port
- RS-232 Bus-Pin ESD Protection Exceeds ± 15 kV Using Human-Body Model (HBM)
- Meets or Exceeds the Requirements of TIA/EIA-232-F and ITU v.28 Standards
- Operates With 3-V to 5.5-V V_{CC} Supply
- Three Drivers and Five Receivers
- Operates Up To 250 kbit/s
- Designed to Transmit at a Data Rate of 250 kbit/s
- Low Standby Current . . . 1 μ A Typical
- External Capacitors . . . $4 \times 0.1 \mu$ F
- Accepts 5-V Logic Input With 3.3-V Supply
- Always-Active Noninverting Receiver Output (ROUT2B)
- Alternative High-Speed Pin-Compatible Device (1 Mbit/s)
 - SNx5C3243
- Serial-Mouse Driveability
- Auto-Powerdown Feature to Disable Driver Outputs When No Valid RS-232 Signal Is Sensed
- Applications
 - Battery-Powered Systems, PDAs, Notebooks, Laptops, Palmtop PCs, and Hand-Held Equipment

DB, DW, OR PW PACKAGE
(TOP VIEW)



description/ordering information

The MAX3243 consists of three line drivers, five line receivers, and a dual charge-pump circuit with ± 15 -kV ESD (HBM) protection pin to pin (serial-port connection pins, including GND). The device meets the requirements of TIA/EIA-232-F and provides the electrical interface between an asynchronous communication controller and the serial-port connector. This combination of drivers and receivers matches that needed for the typical serial port used in an IBM PC/AT, or compatible. The charge pump and four small external capacitors allow operation from a single 3-V to 5.5-V supply. In addition, the device includes an always-active noninverting output (ROUT2B), which allows applications using the ring indicator to transmit data while the device is powered down. The device operates at data signaling rates up to 250 kbit/s and a maximum of 30-V/ μ s driver output slew rate.



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MAX3243**3-V TO 5.5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER****WITH ± 15 -kV ESD (HBM) PROTECTION**

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description/ordering information (continued)

Flexible control options for power management are available when the serial port is inactive. The auto-powerdown feature functions when $\overline{\text{FORCEON}}$ is low and $\overline{\text{FORCEOFF}}$ is high. During this mode of operation, if the device does not sense a valid RS-232 signal, the driver outputs are disabled. If $\overline{\text{FORCEOFF}}$ is set low, both drivers and receivers (except ROUT2B) are shut off, and the supply current is reduced to 1 μA . Disconnecting the serial port or turning off the peripheral drivers causes the auto-powerdown condition to occur.

Auto-powerdown can be disabled when $\overline{\text{FORCEON}}$ and $\overline{\text{FORCEOFF}}$ are high and should be done when driving a serial mouse. With auto-powerdown enabled, the device is activated automatically when a valid signal is applied to any receiver input. The $\overline{\text{INVALID}}$ output is used to notify the user if an RS-232 signal is present at any receiver input. $\overline{\text{INVALID}}$ is high (valid data) if any receiver input voltage is greater than 2.7 V or less than -2.7 V or has been between -0.3 V and 0.3 V for less than 30 μs . $\overline{\text{INVALID}}$ is low (invalid data) if all receiver input voltages are between -0.3 V and 0.3 V for more than 30 μs . Refer to Figure 5 for receiver input levels.

ORDERING INFORMATION

TA	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	SOIC (DW)	Tube of 20	MAX3243CDW	MAX3243C
		Reel of 1000	MAX3243CDWR	
	SSOP (DB)	Tube of 50	MAX3243CDB	MAX3243C
		Reel of 2000	MAX3243CDBR	
	TSSOP (PW)	Tube of 50	MAX3243CPW	MA3243C
		Reel of 2000	MAX3243CPWR	
-40°C to 85°C	SOIC (DW)	Tube of 20	MAX3243IDW	MAX3243I
		Reel of 1000	MAX3243IDWR	
	SSOP (DB)	Tube of 50	MAX3243IDB	MAX3243I
		Reel of 2000	MAX3243IDBR	
	TSSOP (PW)	Tube of 50	MAX3243IPW	MB3243I
		Reel of 2000	MAX3243IPWR	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Function Tables**EACH DRIVER**

INPUTS				OUTPUT DOUT	DRIVER STATUS
DIN	FORCEON	$\overline{\text{FORCEOFF}}$	VALID RIN RS-232 LEVEL		
X	X	L	X	Z	Powered off
L	H	H	X	H	Normal operation with auto-powerdown disabled
H	H	H	X	L	
L	L	H	Yes	H	Normal operation with auto-powerdown enabled
H	L	H	Yes	L	
L	L	H	No	Z	Powered off by auto-powerdown feature
H	L	H	No	Z	

H = high level, L = low level, X = irrelevant, Z = high impedance

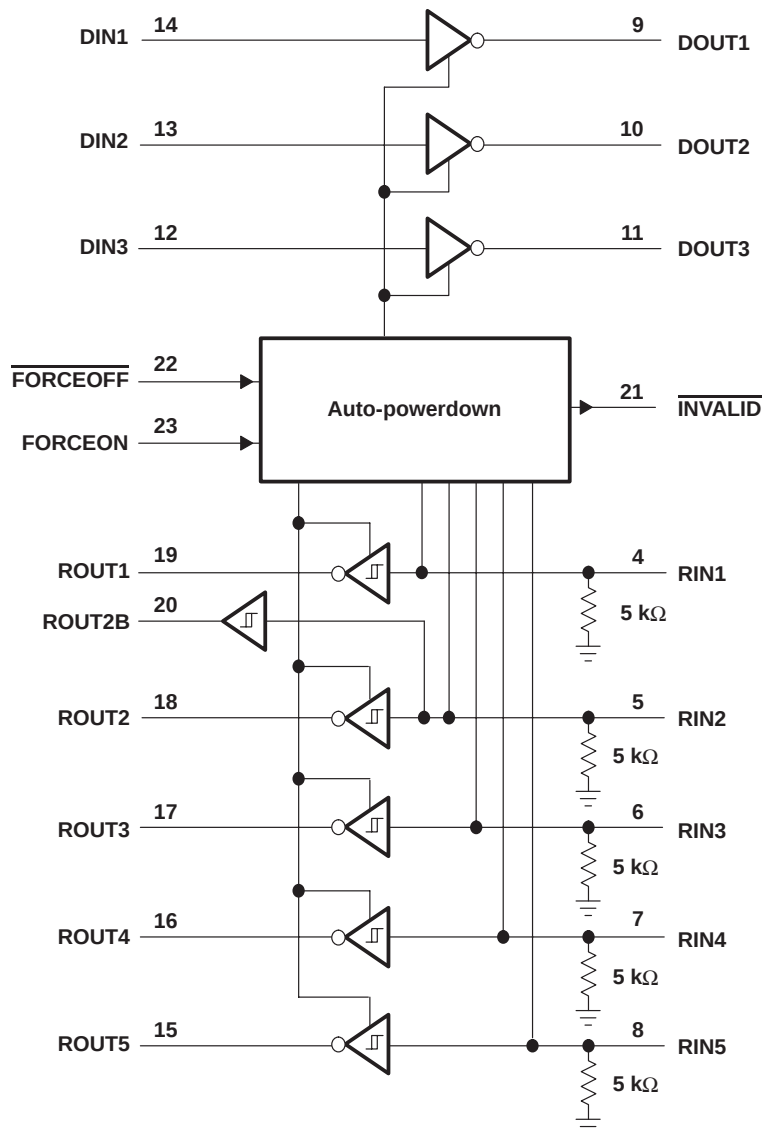


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EACH RECEIVER						
INPUTS				OUTPUTS		RECEIVER STATUS
RIN2	RIN1, RIN3–RIN5	$\overline{\text{FORCEOFF}}$	VALID RIN RS-232 LEVEL	ROUT2B	ROUT	
L	X	L	X	L	Z	Powered off while ROUT2B is active
H	X	L	X	H	Z	
L	L	H	Yes	L	H	Normal operation with auto-powerdown disabled/enabled
L	H	H	Yes	L	L	
H	L	H	Yes	H	H	
H	H	H	Yes	H	L	
Open	Open	H	No	L	H	

H = high level, L = low level, X = irrelevant, Z = high impedance (off), Open = input disconnected or connected driver off

logic diagram (positive logic)



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} (see Note 1)	–0.3 V to 6 V
Positive output supply voltage range, $V+$ (see Note 1)	–0.3 V to 7 V
Negative output supply voltage range, $V-$ (see Note 1)	0.3 V to –7 V
Supply voltage difference, $V+ - V-$ (see Note 1)	13 V
Input voltage range, V_I : Driver ($\overline{\text{FORCEOFF}}$, FORCEON)	–0.3 V to 6 V
Receiver	–25 V to 25 V
Output voltage range, V_O : Driver	–13.2 V to 13.2 V
Receiver (INVALID)	–0.3 V to $V_{CC} + 0.3$ V
Package thermal impedance, θ_{JA} (see Notes 2 and 3): DB package	62°C/W
DW package	46°C/W
PW package	62°C/W
Operating virtual junction temperature, T_J	150°C
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltages are with respect to network GND.

2. Maximum power dissipation is a function of $T_J(\text{max})$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(\text{max}) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.

3. The package thermal impedance is calculated in accordance with JEDEC 51-7.

recommended operating conditions (see Note 4 and Figure 6)

			MIN	NOM	MAX	UNIT
Supply voltage		$V_{CC} = 3.3$ V	3	3.3	3.6	V
		$V_{CC} = 5$ V	4.5	5	5.5	
V_{IH}	Driver and control high-level input voltage	$\overline{\text{DIN}}$, $\overline{\text{FORCEOFF}}$, FORCEON	$V_{CC} = 3.3$ V		2	V
			$V_{CC} = 5$ V		2.4	
V_{IL}	Driver and control low-level input voltage	$\overline{\text{DIN}}$, $\overline{\text{FORCEOFF}}$, FORCEON			0.8	V
V_I	Driver and control input voltage	$\overline{\text{DIN}}$, $\overline{\text{FORCEOFF}}$, FORCEON	0		5.5	V
V_I	Receiver input voltage		–25		25	V
T_A	Operating free-air temperature	MAX3243C	0		70	°C
		MAX3243I	–40		85	

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at $V_{CC} = 3.3$ V $\pm$ 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at $V_{CC} = 5$ V $\pm$ 0.5 V.

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

PARAMETER		TEST CONDITIONS		MIN	TYP [‡]	MAX	UNIT
I_I	Input leakage current	$\overline{\text{FORCEOFF}}$, FORCEON		± 0.01		± 1	μ A
I_{CC}	Supply current	Auto-powerdown disabled	No load, $\overline{\text{FORCEOFF}}$ and FORCEON at V_{CC}	0.3		1	mA
		Powered off	$V_{CC} = 3.3$ V or 5 V, $T_A = 25^\circ\text{C}$ No load, $\overline{\text{FORCEOFF}}$ at GND	1		10	μ A
		Auto-powerdown enabled	No load, $\overline{\text{FORCEOFF}}$ at V_{CC} , FORCEON at GND, All RIN are open or grounded, All DIN are grounded	1		10	

[‡] All typical values are at $V_{CC} = 3.3$ V or $V_{CC} = 5$ V, and $T_A = 25^\circ\text{C}$.

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at $V_{CC} = 3.3$ V $\pm$ 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at $V_{CC} = 5$ V $\pm$ 0.5 V.



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DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
V _{OH} High-level output voltage	All DOUT at R _L = 3 k Ω to GND	5	5.4		V
V _{OL} Low-level output voltage	All DOUT at R _L = 3 k Ω to GND	-5	-5.4		V
V _O Output voltage (mouse driveability)	DIN1 = DIN2 = GND, DIN3 = V _{CC} , 3-k Ω to GND at DOUT3, DOUT1 = DOUT2 = 2.5 mA	± 5			V
I _{IH} High-level input current	V _I = V _{CC}		± 0.01	± 1	μ A
I _{IL} Low-level input current	V _I at GND		± 0.01	± 1	μ A
I _{OS} Short-circuit output current [‡]	V _{CC} = 3.6 V, V _O = 0 V V _{CC} = 5.5 V, V _O = 0 V		± 35	± 60	mA
r _o Output resistance	V _{CC} , V ₊ , and V ₋ = 0 V, V _O = ± 2 V	300	10M		Ω
I _{off} Output leakage current	$\overline{\text{FORCEOFF}}$ = GND V _O = ± 12 V, V _{CC} = 3 V to 3.6 V V _O = ± 10 V, V _{CC} = 4.5 V to 5.5 V			± 25 ± 25	μ A

[†] All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

[‡] Short-circuit durations should be controlled to prevent exceeding the device absolute power dissipation ratings, and not more than one output should be shorted at a time.

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V $\pm$ 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V $\pm$ 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
Maximum data rate	C _L = 1000 pF, One DOUT switching, R _L = 3 k Ω , See Figure 1	150	250		kbit/s
t _{sk(p)} Pulse skew [§]	C _L = 150 pF to 2500 pF, R _L = 3 k Ω to 7 k Ω , See Figure 2		100		ns
SR(tr) Slew rate, transition region (see Figure 1)	V _{CC} = 3.3 V, R _L = 3 k Ω to 7 k Ω C _L = 150 pF to 1000 pF C _L = 150 pF to 2500 pF	6 4		30 30	V/ μ s

[†] All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

[§] Pulse skew is defined as |t_{pLH} – t_{pHL}| of each channel of the same device.

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V $\pm$ 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V $\pm$ 0.5 V.



RECEIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
V _{OH} High-level output voltage	I _{OH} = -1 mA	V _{CC} - 0.6 V	V _{CC} - 0.1 V		V
V _{OL} Low-level output voltage	I _{OL} = 1.6 mA			0.4	V
V _{IT+} Positive-going input threshold voltage	V _{CC} = 3.3 V		1.6	2.4	V
	V _{CC} = 5 V		1.9	2.4	
V _{IT-} Negative-going input threshold voltage	V _{CC} = 3.3 V	0.6	1.1		V
	V _{CC} = 5 V	0.8	1.4		
V _{hys} Input hysteresis (V _{IT+} - V _{IT-})			0.5		V
I _{off} Output leakage current (except ROUT2B)	FORCEOFF = 0 V		±0.05	±10	μA
r _i Input resistance	V _I = ±3 V to ±25 V	3	5	7	kΩ

[†] All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

NOTE 4: Test conditions are C1-C4 = 0.1 μF at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μF, C2-C4 = 0.33 μF at V_{CC} = 5 V ± 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4)

PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
t _{PLH} Propagation delay time, low- to high-level output	C _L = 150 pF, See Figure 3		150		ns
t _{PHL} Propagation delay time, high- to low-level output			150		ns
t _{en} Output enable time	C _L = 150 pF, R _L = 3 kΩ, See Figure 4		200		ns
t _{dis} Output disable time			200		ns
t _{sk(p)} Pulse skew [‡]	See Figure 3		50		ns

[†] All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

[‡] Pulse skew is defined as |t_{PLH} - t_{PHL}| of each channel of the same device.

NOTE 4: Test conditions are C1-C4 = 0.1 μF at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μF, C2-C4 = 0.33 μF at V_{CC} = 5 V ± 0.5 V.

AUTO-POWERDOWN SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
$V_{T+}(\text{valid})$	Receiver input threshold for INVALID high-level output voltage $\text{FORCEON} = \text{GND}, \text{FORCEOFF} = V_{CC}$			2.7	V
$V_{T-}(\text{valid})$	Receiver input threshold for INVALID high-level output voltage $\text{FORCEON} = \text{GND}, \text{FORCEOFF} = V_{CC}$	-2.7			V
$V_{T}(\text{invalid})$	Receiver input threshold for INVALID low-level output voltage $\text{FORCEON} = \text{GND}, \text{FORCEOFF} = V_{CC}$	-0.3		0.3	V
V_{OH}	INVALID high-level output voltage $I_{OH} = -1 \text{ mA}, \text{FORCEON} = \text{GND}, \text{FORCEOFF} = V_{CC}$	$V_{CC} - 0.6$			V
V_{OL}	INVALID low-level output voltage $I_{OL} = 1.6 \text{ mA}, \text{FORCEON} = \text{GND}, \text{FORCEOFF} = V_{CC}$			0.4	V

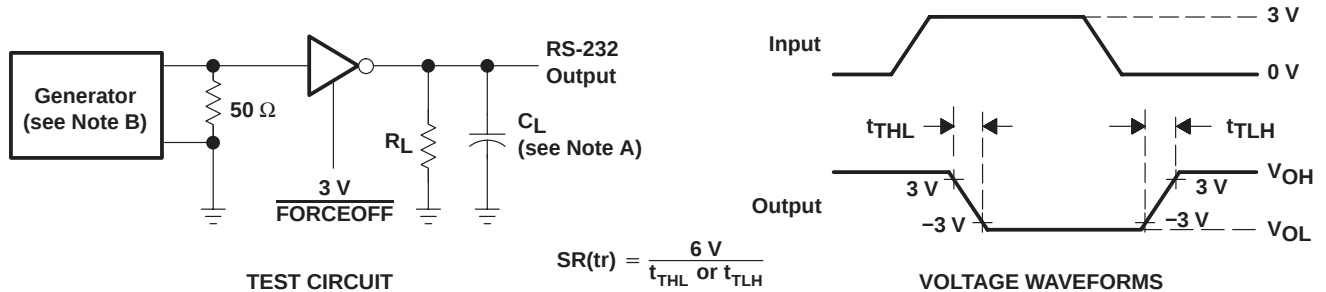
[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^\circ\text{C}$.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

PARAMETER	MIN	TYP [†]	MAX	UNIT
t_{valid}		1		μs
t_{invalid}		30		μs
t_{en}		100		μs

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^\circ\text{C}$.

PARAMETER MEASUREMENT INFORMATION

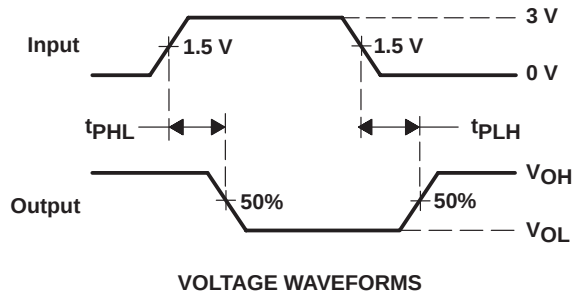
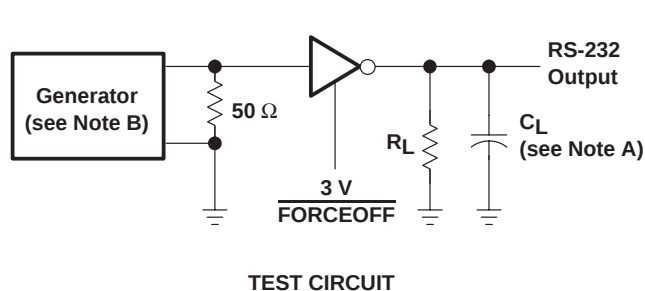


NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_r \leq 10 \text{ ns}$, $t_f \leq 10 \text{ ns}$.

Figure 1. Driver Slew Rate

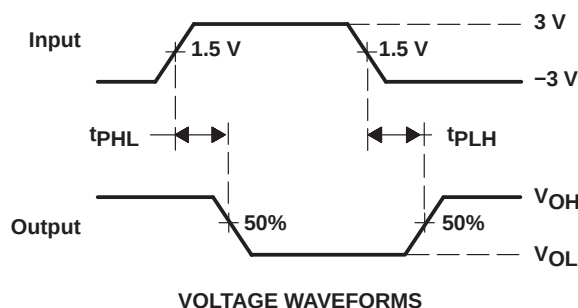
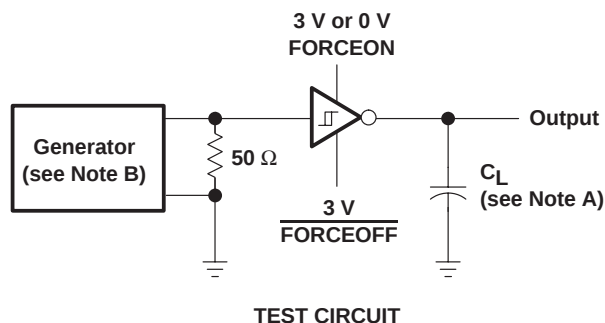
PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_r \leq 10$ ns, $t_f \leq 10$ ns.

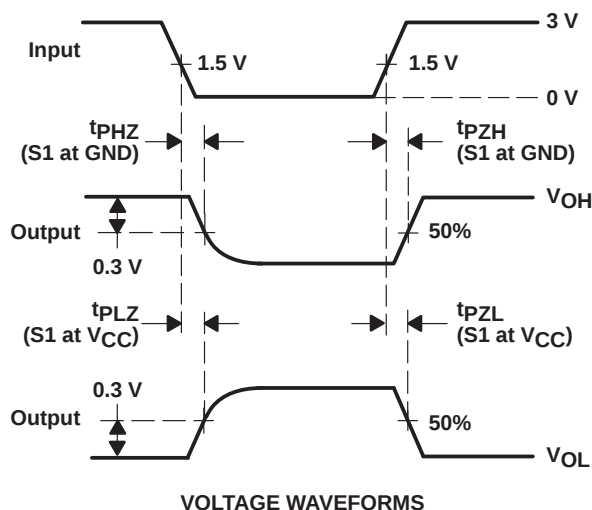
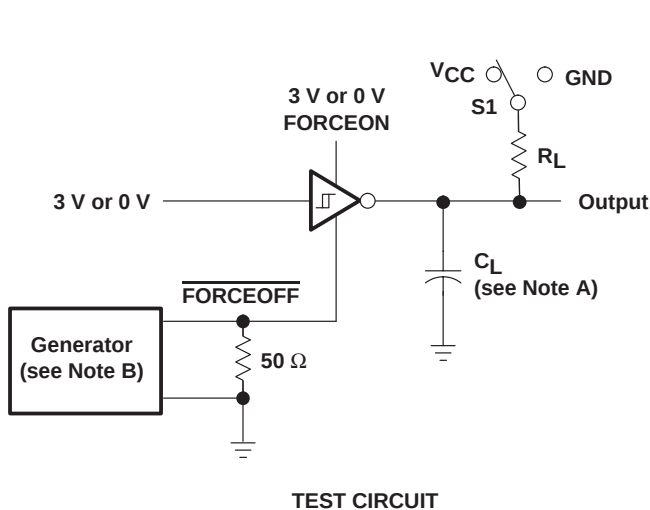
Figure 2. Driver Pulse Skew



NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: $Z_O = 50 \Omega$, 50% duty cycle, $t_r \leq 10$ ns, $t_f \leq 10$ ns.

Figure 3. Receiver Propagation Delay Times



NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: $Z_O = 50 \Omega$, 50% duty cycle, $t_r \leq 10$ ns, $t_f \leq 10$ ns.

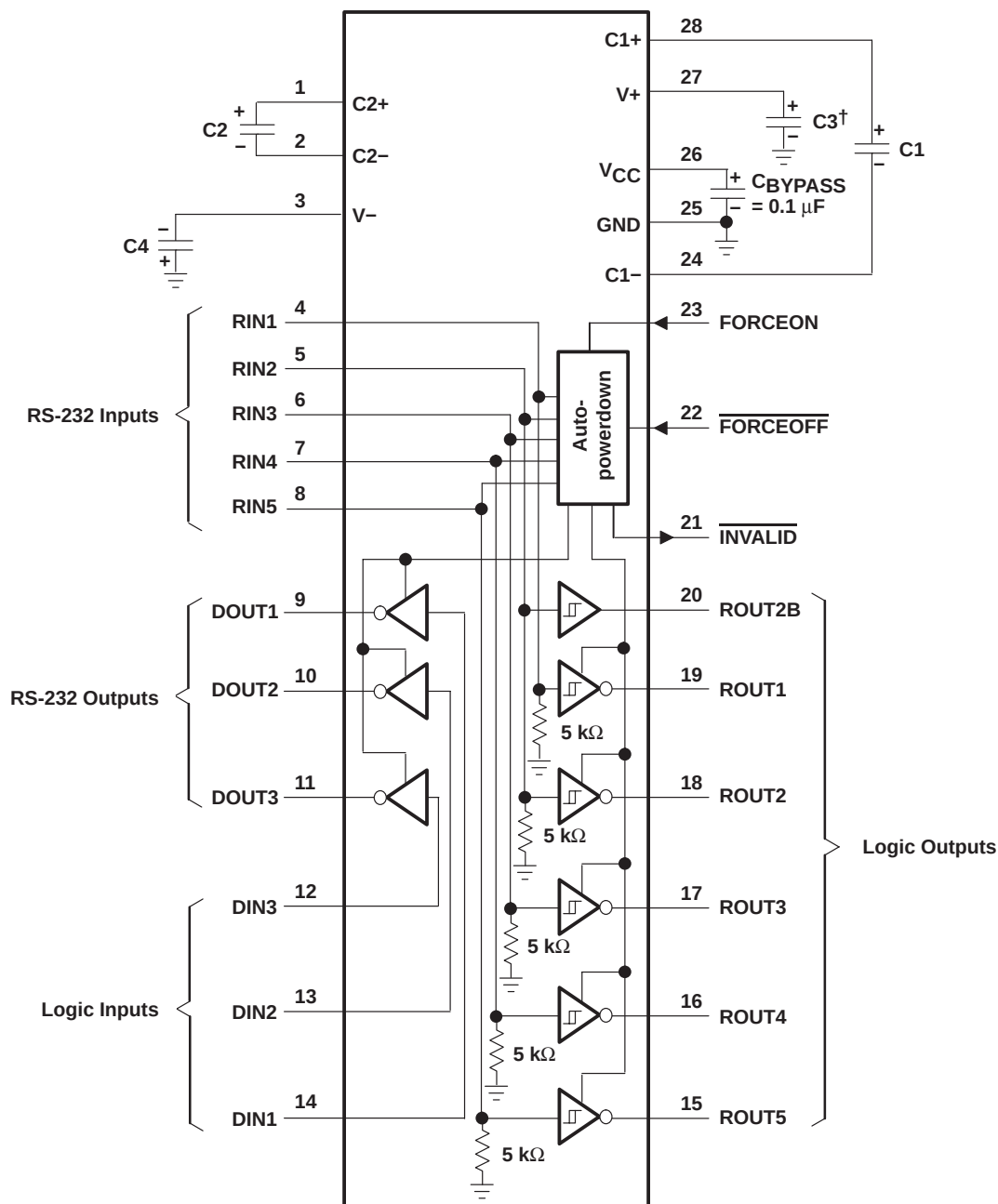
C. t_{PLZ} and t_{PHZ} are the same as t_{dis} .

D. t_{PZL} and t_{PZH} are the same as t_{en} .

Figure 4. Receiver Enable and Disable Times

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APPLICATION INFORMATION



† C3 can be connected to V_{CC} or GND.

NOTES: A. Resistor values shown are nominal.

B. Nonpolarized ceramic capacitors are acceptable. If polarized tantalum or electrolytic capacitors are used, they should be connected as shown.

V_{CC} vs CAPACITOR VALUES

V_{CC}	C1	C2, C3, and C4
3.3 V $\pm$ 0.3 V	0.1 μ F	0.1 μ F
5 V $\pm$ 0.5 V	0.047 μ F	0.33 μ F
3 V to 5.5 V	0.1 μ F	0.47 μ F

Figure 6. Typical Operating Circuit and Capacitor Values

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
MAX3243CDB	ACTIVE	SSOP	DB	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MAX3243C	Samples
MAX3243CDBG4	ACTIVE	SSOP	DB	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MAX3243C	Samples
MAX3243CDBR	ACTIVE	SSOP	DB	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MAX3243C	Samples
MAX3243CDBRE4	ACTIVE	SSOP	DB	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MAX3243C	Samples
MAX3243CDBG4	ACTIVE	SSOP	DB	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MAX3243C	Samples
MAX3243CDW	ACTIVE	SOIC	DW	28	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MAX3243C	Samples
MAX3243CDWE4	ACTIVE	SOIC	DW	28	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MAX3243C	Samples
MAX3243CDWG4	ACTIVE	SOIC	DW	28	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MAX3243C	Samples
MAX3243CDWR	ACTIVE	SOIC	DW	28	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MAX3243C	Samples
MAX3243CDWRG4	ACTIVE	SOIC	DW	28	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MAX3243C	Samples
MAX3243CPW	ACTIVE	TSSOP	PW	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MA3243C	Samples
MAX3243CPWE4	ACTIVE	TSSOP	PW	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MA3243C	Samples
MAX3243CPWG4	ACTIVE	TSSOP	PW	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MA3243C	Samples
MAX3243CPWR	ACTIVE	TSSOP	PW	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MA3243C	Samples
MAX3243CPWRE4	ACTIVE	TSSOP	PW	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MA3243C	Samples
MAX3243CPWRG4	ACTIVE	TSSOP	PW	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MA3243C	Samples
MAX3243IDB	ACTIVE	SSOP	DB	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	MAX3243I	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
MAX3243IDBG4	ACTIVE	SSOP	DB	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	MAX3243I	Samples
MAX3243IDBR	ACTIVE	SSOP	DB	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	MAX3243I	Samples
MAX3243IDBRE4	ACTIVE	SSOP	DB	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	MAX3243I	Samples
MAX3243IDBRG4	ACTIVE	SSOP	DB	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	MAX3243I	Samples
MAX3243IDW	ACTIVE	SOIC	DW	28	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	MAX3243I	Samples
MAX3243IDWG4	ACTIVE	SOIC	DW	28	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	MAX3243I	Samples
MAX3243IDWR	ACTIVE	SOIC	DW	28	1000	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	-40 to 85	MAX3243I	Samples
MAX3243IDWRE4	ACTIVE	SOIC	DW	28	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	MAX3243I	Samples
MAX3243IDWRG4	ACTIVE	SOIC	DW	28	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	MAX3243I	Samples
MAX3243IPW	ACTIVE	TSSOP	PW	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	MB3243I	Samples
MAX3243IPWG4	ACTIVE	TSSOP	PW	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	MB3243I	Samples
MAX3243IPWR	ACTIVE	TSSOP	PW	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	MB3243I	Samples
MAX3243IPWRE4	ACTIVE	TSSOP	PW	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	MB3243I	Samples
MAX3243IPWRG4	ACTIVE	TSSOP	PW	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	MB3243I	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF MAX3243 :

- Enhanced Product: [MAX3243-EP](#)

NOTE: Qualified Version Definitions:

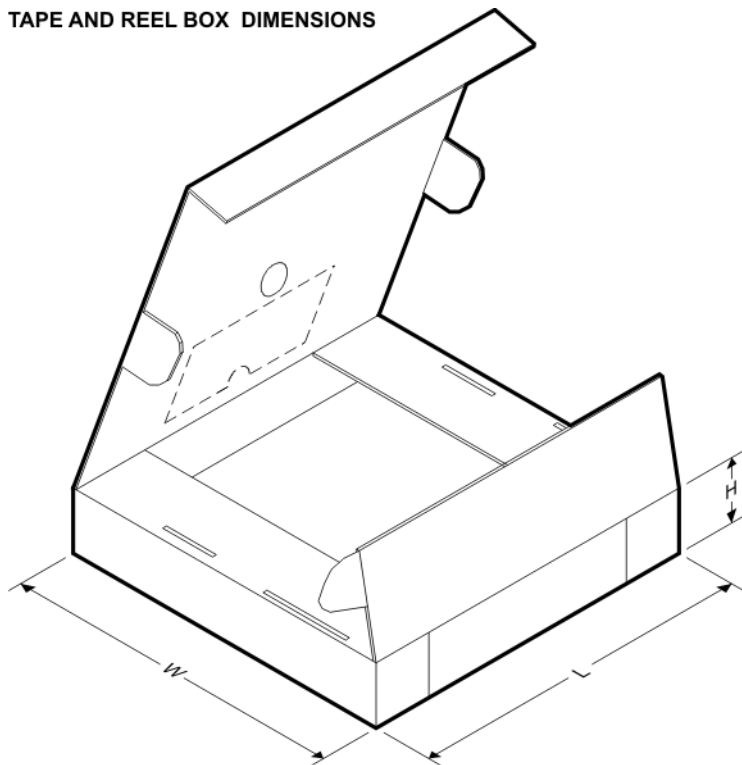
- Enhanced Product - Supports Defense, Aerospace and Medical Applications

TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
MAX3243CDBR	SSOP	DB	28	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
MAX3243CDWR	SOIC	DW	28	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1
MAX3243CPWR	TSSOP	PW	28	2000	330.0	16.4	6.9	10.2	1.8	12.0	16.0	Q1
MAX3243IDBR	SSOP	DB	28	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
MAX3243IDWR	SOIC	DW	28	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1
MAX3243IDWRG4	SOIC	DW	28	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1
MAX3243IPWR	TSSOP	PW	28	2000	330.0	16.4	6.9	10.2	1.8	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS

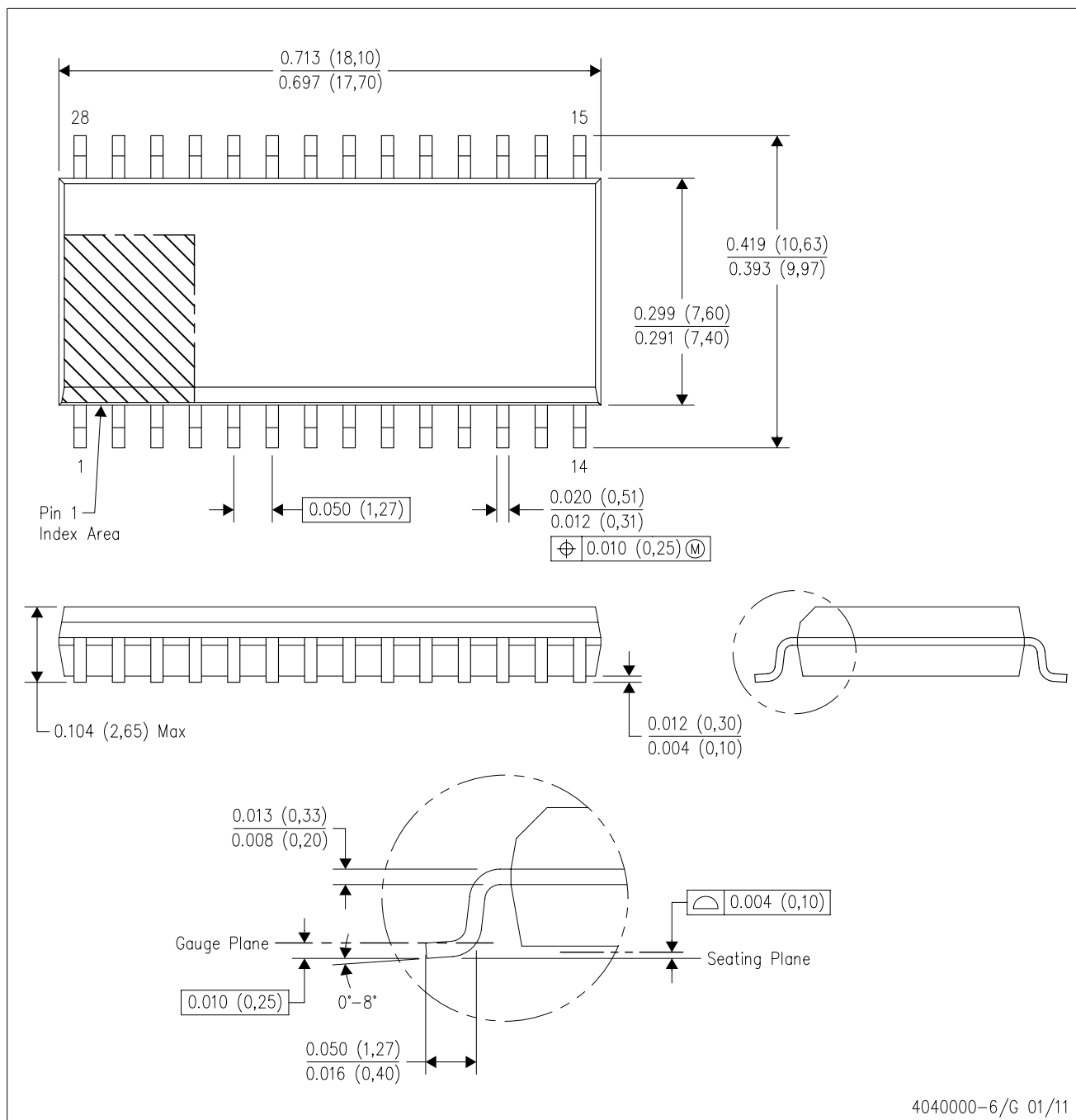


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
MAX3243CDBR	SSOP	DB	28	2000	367.0	367.0	38.0
MAX3243CDWR	SOIC	DW	28	1000	367.0	367.0	55.0
MAX3243CPWR	TSSOP	PW	28	2000	367.0	367.0	38.0
MAX3243IDBR	SSOP	DB	28	2000	367.0	367.0	38.0
MAX3243IDWR	SOIC	DW	28	1000	367.0	367.0	55.0
MAX3243IDWRG4	SOIC	DW	28	1000	367.0	367.0	55.0
MAX3243IPWR	TSSOP	PW	28	2000	367.0	367.0	38.0

DW (R-PDSO-G28)

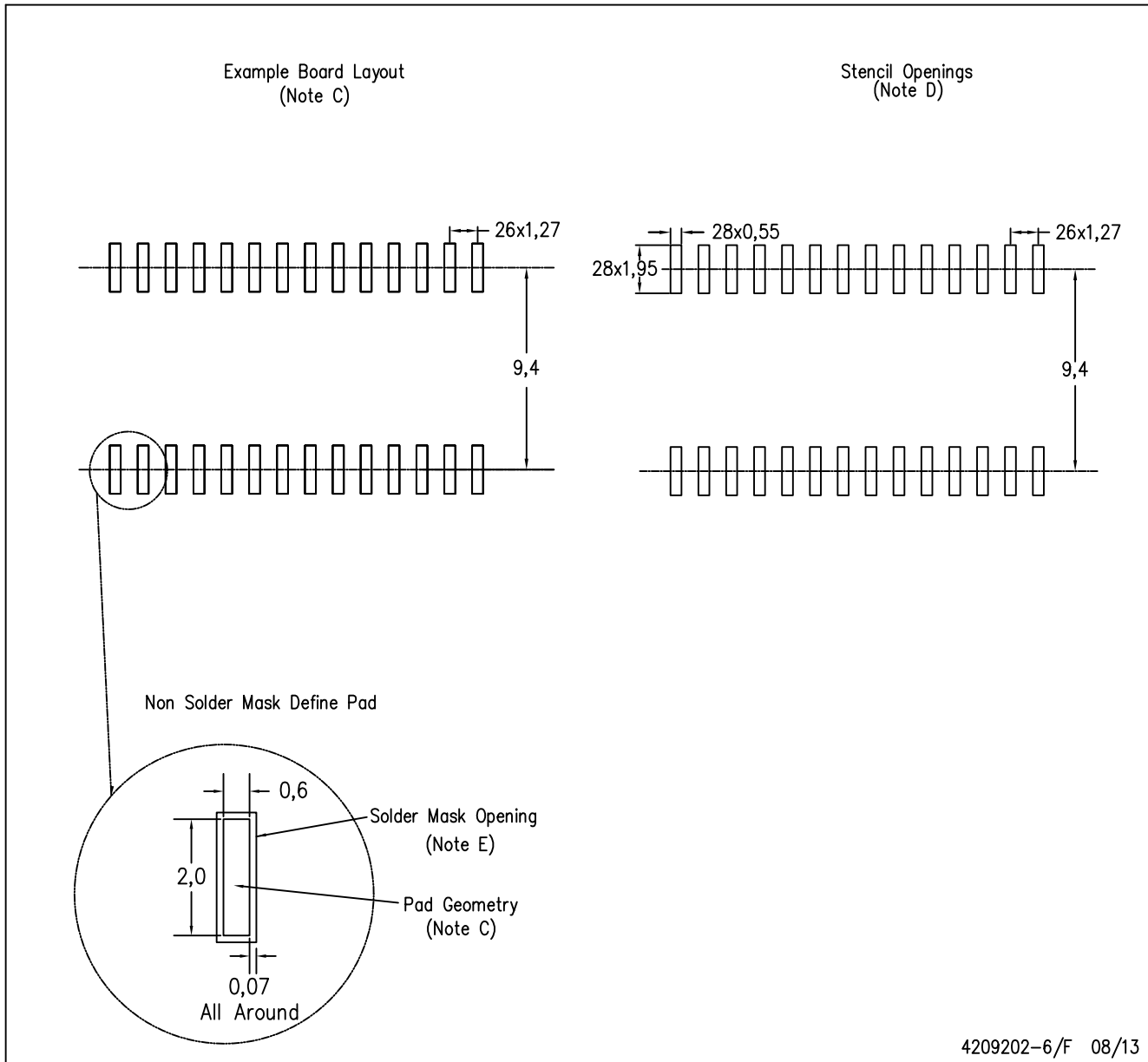
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-013 variation AE.

DW (R-PDSO-G28)

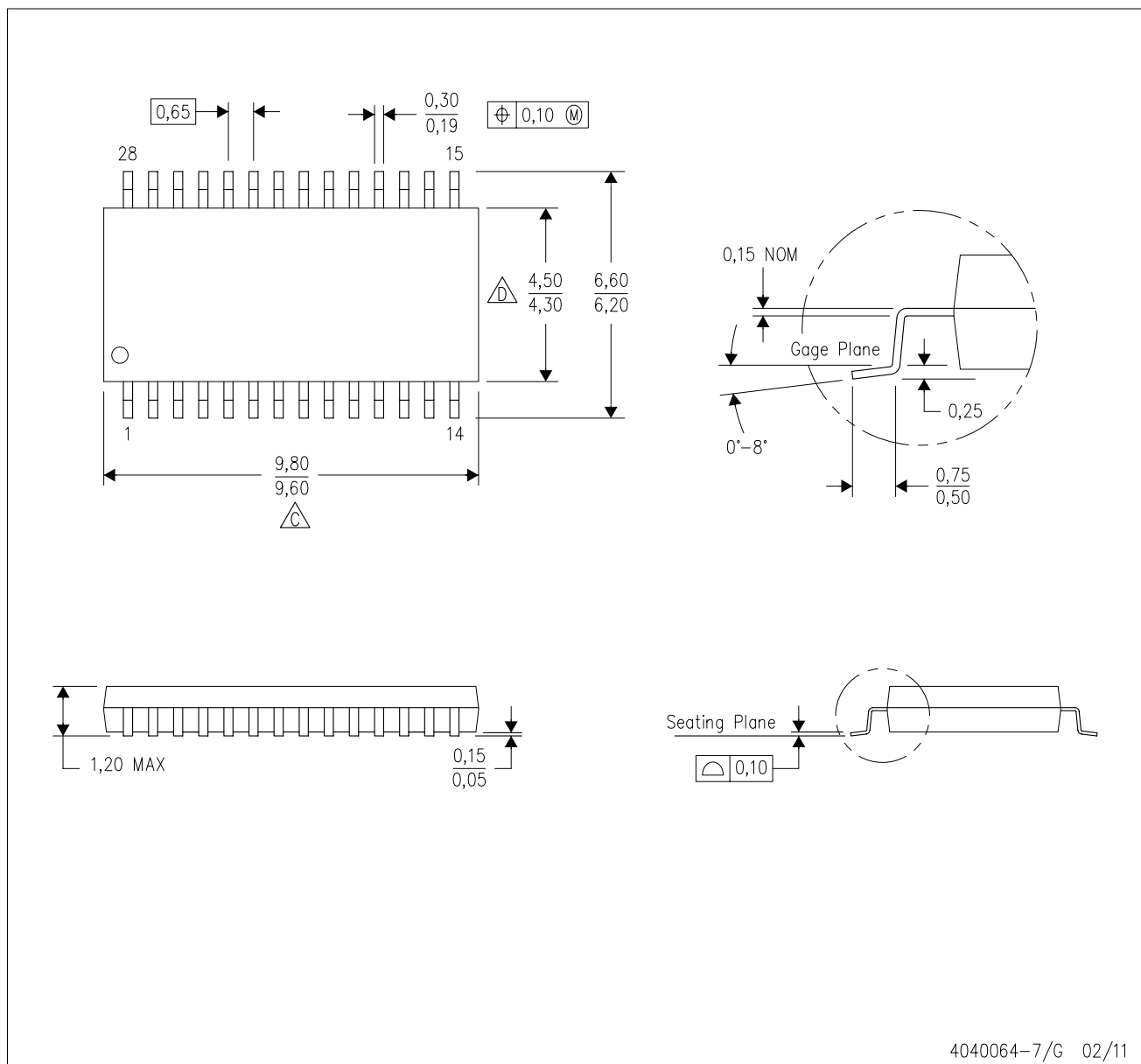
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Refer to IPC7351 for alternate board design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G28)

PLASTIC SMALL OUTLINE

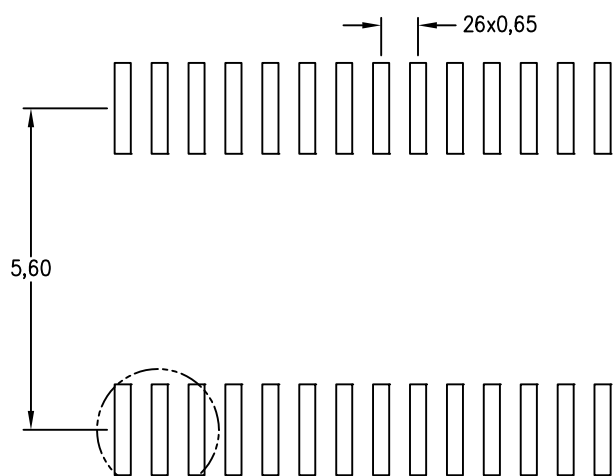


- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

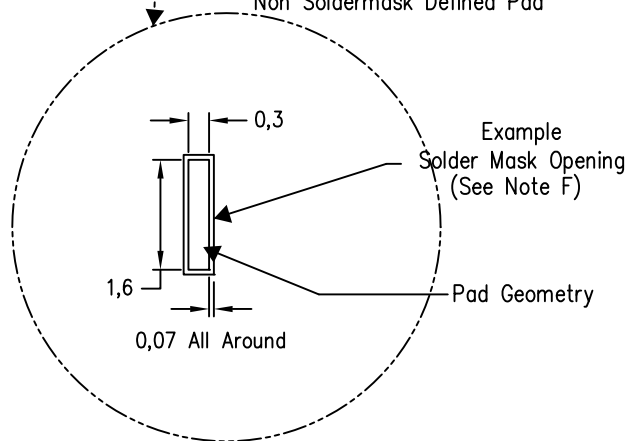
PW (R-PDSO-G28)

PLASTIC SMALL OUTLINE

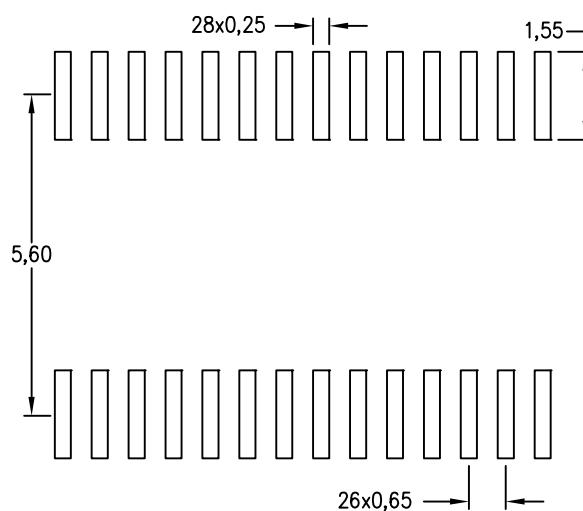
Example Board Layout



Example
Non Soldermask Defined Pad



Stencil Openings
Based on a stencil thickness
of .127mm (.005inch).



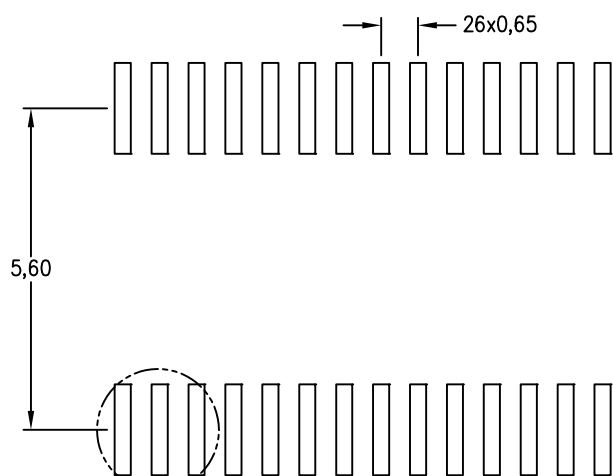
4211284-6/F 12/12

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

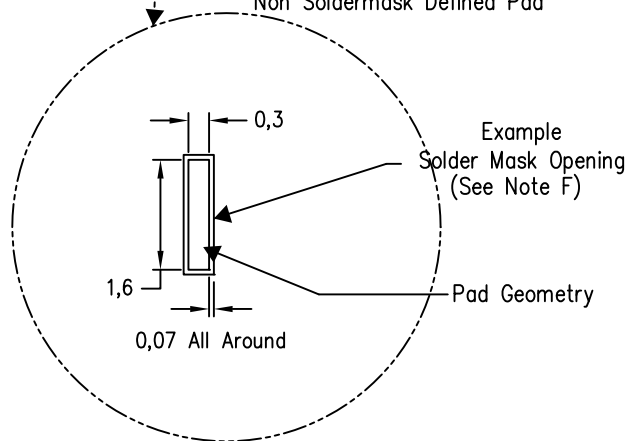
PW (R-PDSO-G28)

PLASTIC SMALL OUTLINE

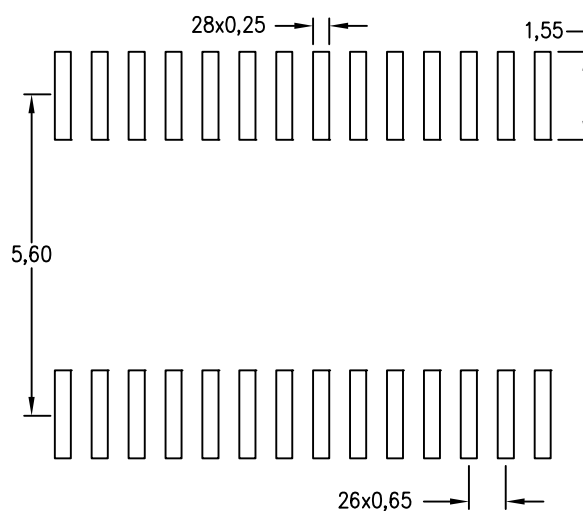
Example Board Layout



Example
Non Soldermask Defined Pad



Stencil Openings
Based on a stencil thickness
of .127mm (.005inch).



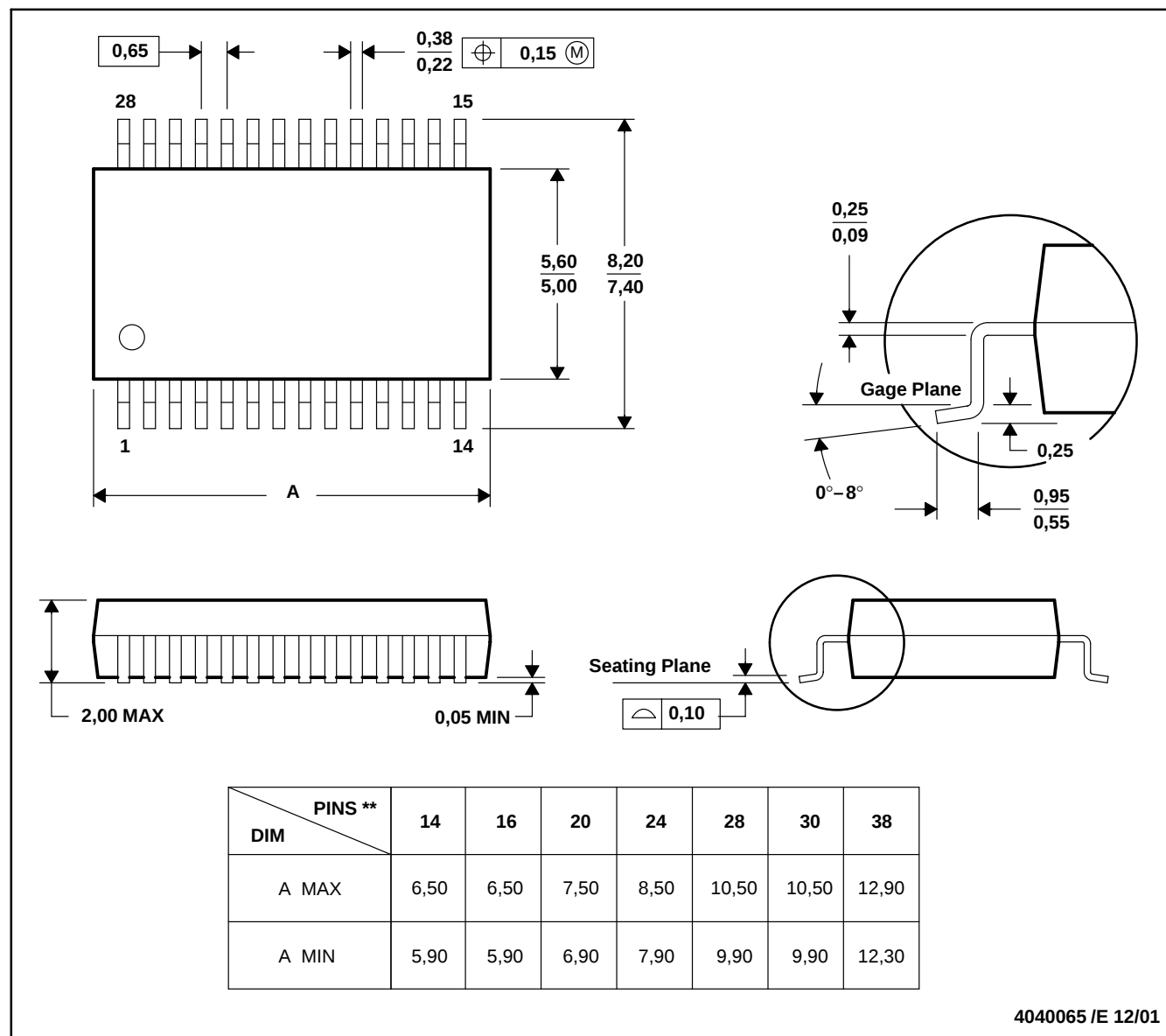
4211284-6/F 12/12

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

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